The Sixth International Symposium on Computer, Consumer and Control
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Special Sessions Call for Papers
The Sixth International Symposium on Computer, Consumer and Control, 2023

Session organizer: Prof. Chih-Hung Wu, Chih-Chin Lai, and Shing-Tai Pan
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Session title: *Engineering Applications of Deep Learning and Artificial Intelligence (EADLAI)*

With the advancement of deep-learning technologies, AI is being realized and integrated into various engineering applications, influencing many aspects of industrial innovation. However, AI-based applications for solving engineering problems must consider many practical issues. It requires extensive research, studies, and innovative ideas to make such applications more robust. This special session addresses the new techniques and innovative methods of deep learning and AI for engineering applications. Research works on designing new AI/deep-learning methods or analyzing existing ones for engineering applications are appreciated. Real cases or stories of practical engineering applications of AI and deep learning are also welcome. We sincerely invite academic researchers and industry professionals from a broad range of disciplines to submit original papers to this special session.

Topics/Areas

All topics in Engineering Applications of AI and Deep Learning (EADLAI) are welcome. Topics of interest include, but are not limited to:

- Automatic Optical Inspection (AOI)
- Internet of Things (IoT)
- Signal Processing for Sound, Image, and Video
- Intelligent Control Systems & Robotics
- Autonomous Vehicles
- Industry 4.0 and Smart Manufactory
- Case Studies of EADLAI

All papers accepted and registered for presentation will be published in the conference proceedings. Excellent papers will be recommended for publication in the special issue of SCI(E)/EI journals. Please note that papers must submit via the submission system website and meet the format of IS3C2023.